

Technical Data Sheet

EP-2101-8

B-Stage Adhesive

Introduction:

EP-2101-8 is designed for use in laminate-based packages and stencil printing. This material is ideal for chip scale packages where tolerance and bleed need to be minimized. EP-2101-8 is a low modulus adhesive ideal for large die sizes.

Features

- Stencil printing
- Low moisture uptake
- Low warpage

UNCURED PROPERTIES		TEST DESCRIPTION	TEST METHOD
Appearance	White	Brookfield DV-III/CP-51 @ 5rpm Brookfield DV-III/CP-51 Visc @ 0.5rpm/Visc @ 5rpm 25% increase in visc. @ 5rpm	FT-P006
Viscosity @ 25°C	32000ps		FT-P008
Thixotropic Index @ 25°C	2.3		FT-P024
Work Life of B-Stage @ 25°C	7 days		FT-P018
Shelf Life @ -40°C	12 months		
CURE CONDITION		TEST DESCRIPTION	TEST METHOD
B-stage Cure Condition		30 min ramp from RT to 100°C+ 60min@100°C	
C-stage Cure Condition		30~60 min ramp from RT to 175°C+ 30min@175°C	
MECHANICAL PROPERTIES-POST CURE		TEST DESCRIPTION	TEST METHOD
Die Shear Strength @ 25°C	>5 Kg/die	2×2mm Si die on Microscope Slide Glass	FT-M012
Die Shear Strength @260°C	>1Kg/die	2×2mm Si die on Microscope Slide Glass	FT-M012

This table is only the test data of Feedpool laboratory, customers still need to do a complete verification test for the product before putting it into production.

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PHYSIOCHEMICAL PROPERTIES-CURED MATERIAL		TEST DESCRIPTION	TEST METHOD
Glass Transition Temperature	40°C	DMA 3 Point Bending Mode	FT-M014
Coefficient of Thermal Expansion		TMA Expansion Mode	FT-M016
Below Tg	105 ppm/°C		
Above Tg	309ppm/°C		
Dynamic Tensile Modulus		Dynamic Mechanical Thermal	FT-M019
@25°C	161 MPa		
@150°C	4 MPa	Dynamic Mechanical Thermal Analysis using <1.6mm thick specimen	
@250°C	7 MPa		

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Instruction

Thawing

Place the container to stand vertically for 30min ~90min.**DO NOT** open the container before adhesive reaches ambient temperature to prevent the moisture condensation. Any moisture that collects on the thawed container should be removed prior to use. Adhesives that appear to have separated should not be used.

Storage

Adhesive should be stored @ -40°C . The shelf life of the material is only valid when the material has been stored at the correct storage condition.

Availability

FeedBond adhesives are packaged in syringes or pots per customer specification. For the details, please contact our Customer Service or sales department.